

Solution Brief

MXM Modules Deliver Powerful GPU Solutions for Edge Computing and AI Applications

ADLINK embedded MXM modules are designed for extreme conditions: limited or no ventilation, small spaces, temperature extremes, and dusty and corrosive environments.



GPUs in Embedded Applications

The Mobile PCI Express Module (MXM) is a standard originally developed for implementing graphics processing units (GPUs) in laptops. With a growing need for GPUs to satisfy emerging artificial intelligence (AI) and edge computing requirements in many embedded market segments, embedded MXM GPU modules can be used for image rendering and general-purpose computing to accelerate parallel computing, imaging processing, and AI inferencing in size, weight, and power (SWaP) constrained environments.

Graphics Solution Comparison

Compared to PCI Express Graphics (PEG) cards used to add GPUs to servers and workstations, MXM GPU modules offer major SWaP advantages. With respect to size, the MXM specification supports two module sizes. Type A MXM modules are less than one-third and one-fifth the size of half- and full-length PEG cards, respectively, as shown in Figure 1. Other benefits embedded MXM GPU module provide are high performance-per-watt and extended temperature options. All are important considerations for edge computing and AI applications to perform reliably in environments with poor ventilation, limited space, temperature extremes, and dust-prone and corrosive conditions.

MXM Modules SWaP-optimized High performance/watt Typically fanless		PEG Cards High performance Easy integration I/O flexibility				
Type B 82 x 105 mm (W x H) 3.2 x 4.1 in.		PEG card widths may vary				
Type A 82 x 70 mm (W x H) 3.2 x 2.8 in.	Half-Length 175 x 107 mm (W x H) 6.9 x 4.2 in.	Full-Length 312 x 107 mm (W x H) 12.3 x 4.2 in.				
312 mm (12.3 in.)						

Figure 1. MXM and PEG card features and form factor comparisons.

MXM GPU Modules at the Edge

Embedded MXM GPUs modules offer the high computing power needed to turn data into intelligence, enabling fast time to action at the edge across industries:



Healthcare

Enable precise diagnosis, stereotactic navigation, and 3D modeling and simulation with accelerated highdefinition image processing on mobile medical imaging equipment.

Smart Manufacturing

Improve workplace safety, productivity, and quality with visionbased guidance, inspection, gauge, <u>and identification</u> on factory floors.

Smart City

Aid traffic analysis, access control, security surveillance, and law enforcement with computer vision and video analysis.

Transportation



Enhance transport safety and efficiency with situational awareness, traffic control, and anomaly detection on trains and in airports.

Aerospace and Defense

Enable communications, surveillance, and reconnaissance with portable ultrasound, airborne radar, aerial infrared imaging, and softwaredefined radio on military aircrafts and naval ships.

ADLINK Embedded MXM GPU Modules

Edge computing and AI requirements vary by application, which can be met by ADLINK's family of scalable embedded MXM GPU modules. They are powered by NVIDIA Quadro[®] embedded GPUs and designed to satisfy unique embedded market needs.

- NVIDIA[®] GPUDirect[™] remote direct memory access (RDMA)¹ for up to 80% increase in data throughput and 60% decrease in I/O latency
- Configurable performance for maximum or consistent responsiveness
- Five-year availability for mission-critical applications that must undergo time-consuming testing and validation

MXM GPU Modules with Turning[™] Architecture

Graphic Core GPU	Quadro [®] T1000				
GPU	Ouadro [®] T1000				
		Quadro [®] RTX3000	Quadro [®] RTX5000		
Memory	4GB GDDR6 memory, 128-bit, Bandwidth: 192 GB/s	6GB GDDR6 memory, 192-bit, Bandwidth: 336 GB/s	16GB GDDR6 memory, 256-bit, Bandwidth: 448 GB/s		
GPGPU Computing					
CUDA Cores	896 CUDA cores, 2.6 TFLOPS Peak FP32 performance	1920 CUDA cores, 5.3 TFLOPS Peak FP32 performance	3072 CUDA cores, 9.4 TFLOPS Peak FP32 performance		
Tensor Cores	N/A	240 Tensor Cores	384 Tensor Cores		
Compute API	CUDA Toolkit 8.0 and above, CUDA Compute version 6.1 and above, OpenCL™ 1.2				
Graphics API	DirectX [®] 12, OpenGL 4.6, Vulkan 1.0 API				
Display					
Display Outputs 4>	4x DisplayPort 1.4a digital video outputs4x DisplayPort 1.4b digital video outputs4K at 120Hz or 8K at 60Hz4K at 120Hz or 8K at 60Hz				
Signal Interface	MXM 3.1, PCI Express Gen3 x16 support				
Mechanicals					
Dimensions (mm)	82 (W) x 70 (D) x 4.8 (H)	82 (W) × 105 (D) × 4.8 (H)	82 (W) x 110 (D) x 4.8 (H)		
Form Factor	Standard MXM 3.1 Type A	Standard MXM 3.1 Type B	Standard MXM 3.1 Type B+		
Environmental					
Operating Temp.	Standard: 0°C to 55°C, ETT: -40°C to 85°C	Standard: 0°C to 55°C, ETT: TBC			
Storage Temp.	-40°C to 85°C				
Module Power Consumption	50W TGP	80W TGP	110W TGP		
SW Support					
OS Support	Windows 10 & Linux Drivers, 64-bit				

MXM GPU Modules with Pascal[™] Architecture

Model Name	EGX-MXM-P1000	EGX-MXM-P2000	EGX-MXM-P3000	EGX-MXM-P5000	
Graphic Core					
GPU	Quadro [®] P1000	Quadro [®] P2000	Quadro [®] P3000	Quadro [®] P5000	
Memory	4GB GDDR5 memory, 128-bit, Bandwidth: 96 GB/s		6GB GDDR5 memory, 192-bit, Bandwidth: 168.2 GB/s	16GB GDDR5 memory, 256-bit, Bandwidth: 192.2 GB/s	
GPGPU Computing					
CUDA Cores	512 CUDA [®] cores, 1.8 TFLOPS SP Peak	768 CUDA [®] cores, 2.3 TFLOPS SP Peak	1280 CUDA [®] cores, 3.9 TFLOPS peak FP32 Performance	2048 CUDA [®] cores, 6.4 TFLOPS peak FP32 performance	
Compute API	CUDA Toolkit 8.0, CUDA Compute version 6.1, OpenCL™ 1.2		CUDA Toolkit 8.0, CUDA Compute version 6.1, OpenCL™ 1.2, Direct Compute		
Graphics API	DirectX [®] 12, OpenGL 4.5, Vulcan 1.0		DirectX [®] 12, OpenGL 4.5, Vulkan 1.0 Shader Model 5.1		
Display					
Display Outputs	4x DisplayPort 1.4 digital video outputs (DP++) 4K at 120Hz or 5K at 60Hz		4x DisplayPort 1.4 digital video outputs (DP++), 1x HDMI, 2x DVI, 1x eDP		
Signal Interface	MXM 3.1, PCI Express Gen3 x16 support				
Mechanicals					
Dimensions (mm)	82 (W) × 70 (D) × 4.8 (H)		82 (W) x 105 (D) x 4.8 (H)		
Form Factor	Standard MXM 3.1 Type A		Standard MXM 3.1 Type B		
Environmental					
Operating Temp.	Standard: 0°C to 55°C, ETT: -40°C to 85°C		0°C to 55°C		
Storage Temp.	-40°C to 85°C		-40°C to 125°C		
Module Power Consumption	48W	58W	75W	100W	
SW Support					
OS Support	Windows 10 & Linux drivers, 64-bit				

1.NVIDIA GPUDirect™ Technology, http://developer.download.nvidia.com/devzone/devcenter/cuda/docs/GPUDirect_Technology_Overview.pdf.

www.adlinktech.com

